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(54) **HEATER APPARATUS-INTEGRATED TOP  
COVER FOR A COMPUTING DEVICE**

(52) **U.S. Cl.**

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**ABSTRACT**

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A computing device includes a top cover, a heater apparatus, a plurality of temperature sensors, and a heating control component. The heater apparatus includes a heater component and a connector, and the heater component is affixed to the top cover. The plurality of temperature sensors are operatively connected to the heating control component. The heating control component configured to manage the heater apparatus using the plurality of temperature sensors.

Information  
Handling  
System  
100

